

SEP 20 2006

AMENDMENTS TO THE CLAIMS:

1. (Currently Amended) A method of making a thin film explosive detonator,
comprising:
forming a substrate layer;
depositing a metal layer of a cation in situ on the substrate layer; and
reacting the metal layer to form a primary explosive layer.
2. (Currently Amended) The method of claim 1, wherein the substrate layer
comprises silicon.
3. (Currently Amended) The method of claim 1, wherein the metal layer comprises
one of copper, nickel, cadmium, and silver.
4. (Currently Amended) The method of claim 1, wherein the metal layer is reacted
with at least one of a gas and liquid phase reactant.
5. (Currently Amended) The method of claim 1, wherein ~~the step of~~ said depositing
a metal layer of a cation in situ on the substrate layer includes depositing the
metal layer by at least one of plasma vapor deposition, chemical vapor deposition,
electroplating, sputtering and sintering.
6. (Currently Amended) The method of claim 1, further comprising depositing an
organic flyer layer on top of the primary explosive layer.
7. (Currently Amended) The method of claim 1, further comprising forming a barrel
in the substrate layer.

8-16 (Cancelled)

17. (New) The method of claim 1, wherein said primary explosive layer is a comprised of an explosive salt with a predetermined thickness.

18. (New) The method of claim 17, wherein said explosive salt is comprised of one of copper azide, nickel azide, cadmium azides, silver azides, and fulminates.

19. (New) The method of claim 1, wherein said primary explosive layer is comprised of copper azide with a predetermined thickness.

20. (New) The method of claim 1, wherein said primary explosive layer is comprised of no more than about 10 milligrams of primary explosive.